



## Product Change Notification / SYST-31YQS834

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### Date:

01-Sep-2021

### Product Category:

Analog Multiplexer/Switch ICs

### PCN Type:

Document Change

### Notification Subject:

Data Sheet - HV2818/HV2918 - No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch

### Affected CPNs:

[SYST-31YQS834\\_Affected\\_CPN\\_09012021.pdf](#)  
[SYST-31YQS834\\_Affected\\_CPN\\_09012021.csv](#)

### Notification Text:

SYST-31YQS834

Microchip has released a new Product Documents for the HV2818/HV2918 - No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch of devices. If you are using one of these devices please read the document located at [HV2818/HV2918 - No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch](#)

**Notification Status:** Final

**Description of Change:** The following is the list of modifications:

1. Updated Note 1 in table Recommended Operating Conditions.
2. Updated parameter "Off Isolation SW to Y" in table AC Electrical Characteristics.
3. Various typographical errors.

**Impacts to Data Sheet:** See above details

**Reason for Change:** To Improve Productivity

**Change Implementation Status:** Complete

**Date Document Changes Effective:** 01 September 2021

**NOTE:** Please be advised that this is a change to the document only the product has not been changed.

**Markings to Distinguish Revised from Unrevised Devices:** N/A

## **Attachments:**

**HV2818/HV2918 - No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

HV2818/R4X

HV2918/R4X



# HV2818/HV2918

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## No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch

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### Features

- 32-Channel (16 2:1 MUX) High-Voltage Analog Switch
- Only +5V Bias Supply Required
- 3.3V and 5V CMOS Input Logic Level
- Asymmetric Switch Topology for Small Size
- 66 MHz Data Shift Clock Frequency
- Low-Parasitic Capacitance
- Low Harmonic Distortion
- DC to 50 MHz Analog Small-Signal Frequency
- 200 kHz to 50 MHz Large Signal Frequency
- -70 dB Typical Off Isolation at 5.0 MHz
- Excellent Noise Immunity
- Cascadable Serial Data Register with Latches
- Integrated Bleed Resistors on the SW Outputs (HV2918 only)

### Applications

- Medical Ultrasound Imaging
- Non-Destructive Testing (NDT) Metal Flaw Detection
- Piezoelectric Transducer Drivers
- Inkjet Printer Head
- Optical MEMS Modules

### General Description

The HV2818/HV2918 devices are low harmonic distortion, low charge injection, 16 2:1 multiplexer/demultiplexer, high-voltage analog switches without high-voltage bias supplies. They are intended for use in applications requiring high-voltage switching controlled by low-voltage control signals, such as medical ultrasound imaging, driving piezoelectric transducers and printers.

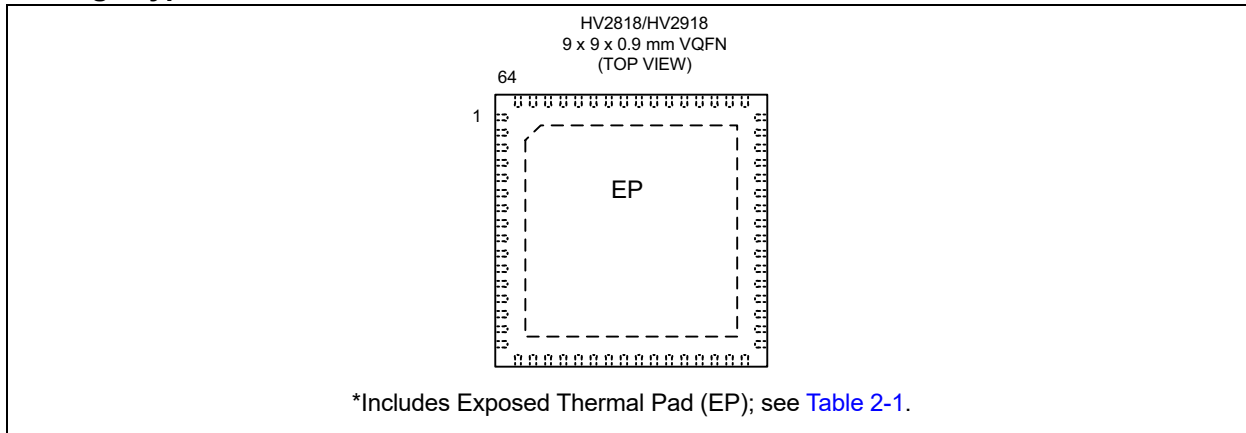
The HV2818/HV2918 are pin-to-pin compatible to high-voltage bias HV2801/HV2901, except for bias voltage pins. The HV2818/HV2918 are available in a 64-pin, 9x9 mm QFN package. The devices have asymmetric topology to implement a small size in low voltage bias high-voltage switches while keeping performance such as peak current. The SW pin can pass high-voltage pulsed signals when the switch is ON. During the OFF state, high-voltage must not be applied to the SW pin due to its asymmetric topology. In medical ultrasound systems, the Y pin must be connected to the analog front end (AFE) and the SW pin must be connected to a single piezoelectric transducer element to avoid high voltage in the SW pin during the switch OFF state.

HV2818 and HV2918 are identical, except for the bleed resistors at the SW pins. HV2818 does not have the bleed resistors at the SW pins like HV2801. HV2918 has the bleed resistors at the SW pins like HV2901. The bleed resistors eliminate possible voltage build-up on capacitive loads such as piezoelectric transducers. The ON/OFF state of the 32 switches is programmed individually through a digital serial interface.

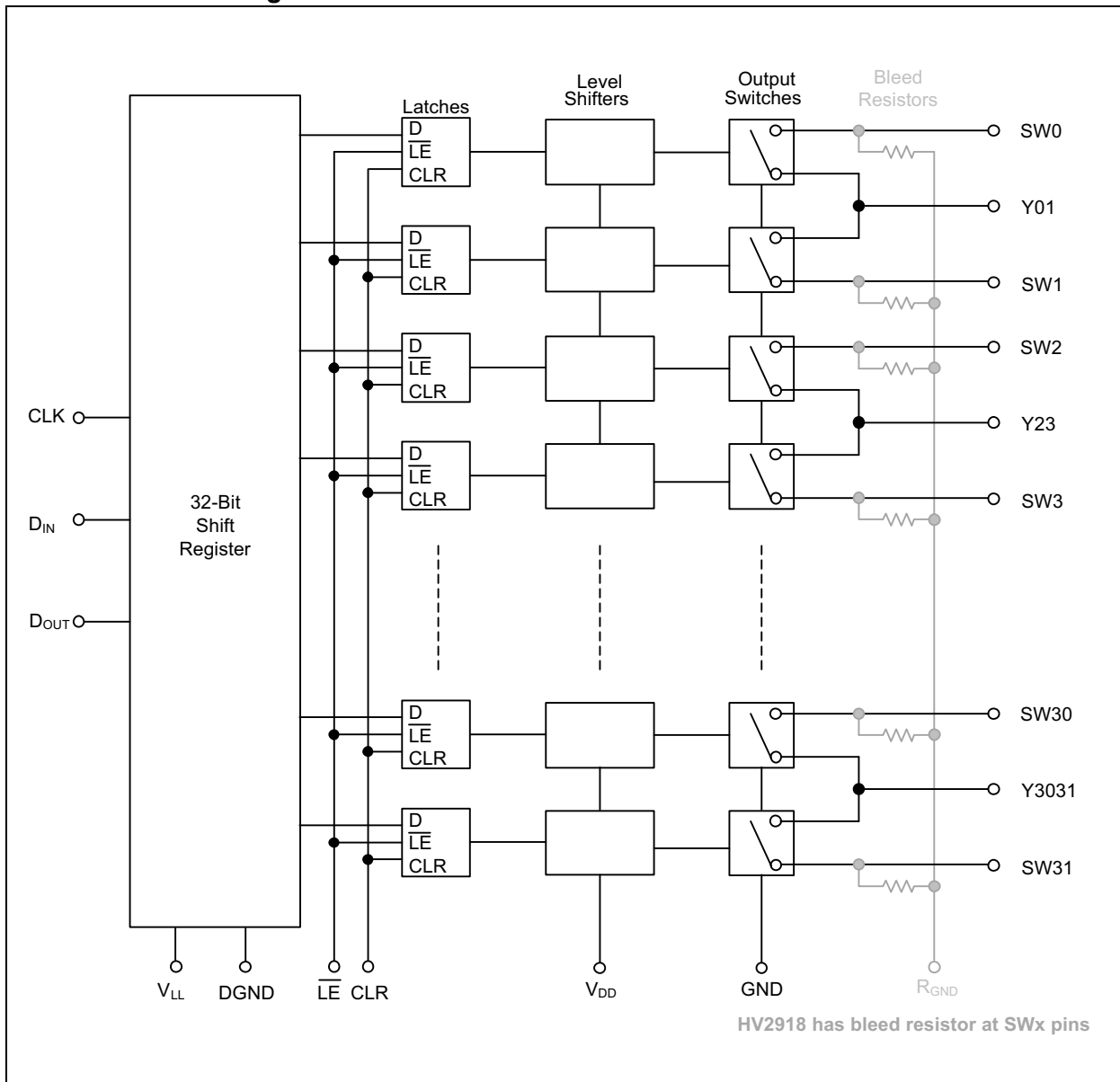
The devices only need a +5V low-voltage bias supply. However, all of the analog switches can pass up to  $\pm 100V$  high-voltage pulsed signals. Like other low-voltage bias switches, the HV2818/HV2918 cannot pass high-voltage DC signals. They can only pass high-voltage pulsed signals up to 2.5  $\mu s$  pulse width. These devices have typical 6 $\Omega$  ON resistance and 50 MHz bandwidth for small signals.

# HV2818/HV2918

## Package Type



## Functional Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

Logic Supply Voltage ( $V_{LL}$ ) .....	-0.5V to 6.6V
Positive Supply Voltage ( $V_{DD}$ ).....	-0.5V to 6.6V
Logic Input Voltage ( $V_{IN}$ ).....	-0.5V to $V_{LL} + 0.3V$
Analog Signal Voltage Y Pin ( $V_Y$ ).....	-110V to +110V
Analog Signal Voltage SW Pin ( $V_{SW}$ ) when the Switch is ON .....	-110V to +110V
Analog Signal Voltage SW Pin ( $V_{SW}$ ) when the Switch is OFF .....	-2V to +2V
Peak Analog Signal Current/Channel ( $I_{PK}$ ) .....	2.7A

† **Notice:** Stresses above those listed under Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

**Note:** Devices are ESD-sensitive. Handling precautions are recommended.

### RECOMMENDED OPERATING CONDITIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Logic Supply Voltage	$V_{LL}$	3	—	5.5	V	—
Positive Supply Voltage	$V_{DD}$	4.5	—	6.3	V	—
Analog Signal Voltage Y Pin Peak-to-Peak	$V_Y$	-100	—	100	V	—
High-Level Input Voltage	$V_{IH}$	$0.9V_{LL}$	—	$V_{LL}$	V	—
Low-Level Input Voltage	$V_{IL}$	0	—	$0.1V_{LL}$	V	—

- Note 1:** Power-up sequence is  $V_{LL}$  first and then  $V_{DD}$ . Power-down sequence is the reverse of power-up.  
**2:**  $V_Y$  and  $V_{SW}$  must be within  $V_{DD}$  and GND or floating during power-up/down transition.  
**3:** Rise and fall times of power supplies,  $V_{LL}$  and  $V_{DD}$  must be greater than 1.0 ms.

### DC ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $V_{DD} = +5V$ ,  $V_{LL} = +5V$ ,  $T_A = +25^\circ C$ . **Boldface** specifications apply over the full operating temperature range.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Small-Signal Switch On-Resistance	$R_{ONS}$	—	6	<b>9</b>	$\Omega$	$I_{SIG} = 5\text{ mA}$
		—	6	<b>9</b>	$\Omega$	$I_{SIG} = 200\text{ mA}$
Small Signal Switch On-Resistance Matching	$\Delta R_{ONS}$	—	—	<b>20</b>	%	$I_{SIG} = 5\text{ mA}$
Large-Signal Switch ON-Resistance	$R_{ONL}$	—	5	—	$\Omega$	$V_{SIG} = 90V$ , $R_{LOAD} = 80\Omega$ <b>(Note 1)</b>
Value of Output Bleed Resistor (HV2918 only)	$R_{INT}$	20	35	50	k $\Omega$	Output switch to $R_{GND}$ $I_{RINT} = 20\text{ }\mu A$
Switch Off Leakage per SW Pin	$I_{SOL}$	—	—	<b>3</b>	$\mu A$	$V_{SIG} = +100V$ , 500 $\mu s$ pulse, see Figure 3-1
		—	—	<b>3</b>	$\mu A$	$V_{SIG} = -100V$ , 100 $\mu s$ pulse, see Figure 3-1 <b>(Note 1)</b>

- Note 1:** Specification is obtained by characterization and is not 100% tested.  
**2:** Design guidance only.

# HV2818/HV2918

## DC ELECTRICAL CHARACTERISTICS (CONTINUED)

Unless otherwise specified,  $V_{DD} = +5V$ ,  $V_{LL} = +5V$ ,  $T_A = +25^\circ C$ . **Boldface** specifications apply over the full operating temperature range.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Switch Off Bias per Y Pin	I <sub>SOB</sub>	—	—	<b>3</b>	μA	V <sub>SIG</sub> = +100V, 500 μs pulse, see <a href="#">Figure 3-2</a>
		—	—	<b>3</b>	mA	V <sub>SIG</sub> = -100V, 100 μs pulse, see <a href="#">Figure 3-2 (Note 1)</a>
HV2818						
Switch Off Bias per SW Pin		—	—	<b>3</b>	μA	V <sub>SIG</sub> = +300 mV, -300 mV, see <a href="#">Figure 3-3</a>
HV2918						
Switch Off Bias of All SW Pins		—	—	<b>10</b>	μA	V <sub>SIG</sub> = +300 mV, -300 mV, see <a href="#">Figure 3-3</a>
DC Offset Switch Off	V <sub>OS</sub>	—	1	<b>10</b>	mV	R <sub>LOAD</sub> = 50 kΩ (HV2818), No load (HV2918) See <a href="#">Figure 3-4</a>
DC Offset Switch On		—	1	<b>10</b>		
Quiescent V <sub>DD</sub> Supply Current	I <sub>DDQ</sub>	—	—	<b>10</b>	μA	All switches OFF
		—	—	<b>10</b>	μA	All switches ON, V <sub>SW</sub> = 1V
Quiescent V <sub>LL</sub> Supply Current	I <sub>LLQ</sub>	—	—	<b>10</b>	μA	All logic inputs are static
Switch Output Peak Current	I <sub>SW</sub>	<b>2</b>	2.7	—	A	V <sub>SIG</sub> duty cycle < 0.1% ( <a href="#">Note 1</a> )
Output Switching Frequency	f <sub>SW</sub>	—	—	<b>50</b>	kHz	Duty cycle = 50% ( <a href="#">Note 1</a> )
Average V <sub>DD</sub> Supply Current	I <sub>DD</sub>	—	7	<b>10</b>	mA	All output switches are turning ON and OFF at 50 kHz with no load
Average V <sub>LL</sub> Supply Current	I <sub>LL</sub>	—	1.3	<b>2.5</b>	mA	f <sub>CLK</sub> = 5.0 MHz
Data Out Source Current	I <sub>SOR</sub>	<b>10</b>	—	—	mA	V <sub>OUT</sub> = V <sub>LL</sub> - 0.7V
Data Out Sink Current	I <sub>SINK</sub>	<b>10</b>	—	—	mA	V <sub>OUT</sub> = 0.7V
Logic Input Capacitance	C <sub>IN</sub>	-	8	—	pF	<a href="#">Note 2</a>

**Note 1:** Specification is obtained by characterization and is not 100% tested.

**2:** Design guidance only.

## AC ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $V_{DD} = +5V$ ,  $V_{LL} = +5V$ ,  $T_{AMB} = +25^\circ C$ . **Boldface** specifications apply over the full operating temperature range.

Parameters	Sym,	Min.	Typ.	Max.	Units.	Conditions
Setup Time before LE Rises	t <sub>SD</sub>	<b>25</b>	—	—	ns	<a href="#">Note 1</a>
Time Width of LE	t <sub>WLE</sub>	<b>12</b>	—	—	ns	<a href="#">Note 1</a>
Clock Delay Time to Data Out	t <sub>DO</sub>	—	—	<b>13.5</b>	ns	—
Time Width of CLR	t <sub>WCLR</sub>	<b>55</b>	—	—	ns	<a href="#">Note 1</a>
Setup Time Data to Clock	t <sub>SU</sub>	<b>1.5</b>	—	—	ns	<a href="#">Note 1</a>
Hold Time Data from Clock	t <sub>H</sub>	<b>1.5</b>	—	—	ns	<a href="#">Note 1</a>
Clock Frequency	f <sub>CLK</sub>	—	—	<b>66</b>	MHz	50% duty cycle, f <sub>DIN</sub> = (1/2)f <sub>CLK</sub> , C <sub>DOUT</sub> = 20 pF ( <a href="#">Note 1</a> )
Clock Rise and Fall Times	t <sub>R</sub> , t <sub>F</sub>	—	—	<b>50</b>	ns	—

**Note 1:** Specification is obtained by characterization and is not 100% tested.

**2:** Design guidance only.

## AC ELECTRICAL CHARACTERISTICS (CONTINUED)

Unless otherwise specified,  $V_{DD} = +5V$ ,  $V_{LL} = +5V$ ,  $T_{AMB} = +25^{\circ}C$ . **Boldface** specifications apply over the full operating temperature range.

Parameters	Sym.	Min.	Typ.	Max.	Units.	Conditions
Turn-On Time	$t_{ON}$	—	—	<b>5</b>	$\mu s$	$V_{SIG} = 5V$ , $R_{LOAD} = 550\Omega$ See <a href="#">Figure 3-5</a>
Turn-Off Time	$t_{OFF}$	—	—	<b>5</b>		
Input Large-Signal Pulse Width	$t_{PW}$	—	—	<b>2.5</b>	$\mu s$	$V_{PULSE} = 0V$ to $\pm 100V$ Measured at 90% amplitude See <a href="#">Figure 3-6 (Note 1)</a>
Maximum $V_{SIG}$ Slew Rate	$dv/dt$	—	—	20	V/ns	<a href="#">Note 1</a>
Analog Small-Signal Frequency	$f_{BWS}$	—	50	—	MHz	<a href="#">Note 1</a>
Off Isolation Y to SW	$K_O$	—	-65	-60	dB	$f = 5.0$ MHz, 1.0 k $\Omega$ /15 pF load See <a href="#">Figure 3-7 (Note 1)</a>
		—	-70	-65		$f = 5.0$ MHz, 50 $\Omega$ load See <a href="#">Figure 3-7 (Note 1)</a>
Off Isolation SW to Y		—	-65	-60	dB	$f = 5.0$ MHz, 1.0 k $\Omega$ /15 pF load See <a href="#">Figure 3-8 (Note 1)</a>
		—	-70	-65		$f = 5.0$ MHz, 50 $\Omega$ load See <a href="#">Figure 3-8 (Note 1)</a>
Switch Crosstalk	$K_{CR}$	—	-70	-60	dB	$f = 5.0$ MHz, 50 $\Omega$ load See <a href="#">Figure 3-9 (Note 1)</a>
Off Capacitance SW to GND	$C_{SG(OFF)}$	—	4	—	pF	$V_{SIG} = 50$ mV at 1 MHz, no load, both SW OFF ( <a href="#">Note 1</a> )
Off Capacitance Y to GND		—	21	—		
On Capacitance SW to GND	$C_{SG(ON)}$	—	22	—	pF	$V_{SIG} = 50$ mV at 1 MHz, no load, one SW ON, one SW OFF ( <a href="#">Note 1</a> )
On Capacitance Y to GND		—	22	—		
Output Voltage Spike at SW	$+V_{SPK}$	—	—	40	mV	$R_{LOAD} = 50\Omega$ See <a href="#">Figure 3-10 (Note 1)</a>
	$-V_{SPK}$	-10	—	—		
Output Voltage Spike at Y	$+V_{SPK}$	—	—	40	mV	$R_{LOAD} = 50\Omega$ See <a href="#">Figure 3-10 (Note 1)</a>
	$-V_{SPK}$	-10	—	—		
Charge Injection at SW	QC	—	50	—	pC	See <a href="#">Figure 3-11 (Note 1)</a>
Charge Injection at Y		—	100	—	pC	See <a href="#">Figure 3-11 (Note 1)</a>
Second Harmonic Distortion	HD2	—	-65	—	dBc	$V_{SIG} = 1.5 V_{PP}$ at 5 MHz, 50 $\Omega$ load ( <a href="#">Note 1</a> )
		—	-63	—	dBc	$V_{SIG} = 1.5 V_{PP}$ at 5 MHz, 1 k $\Omega$ /15 pF load ( <a href="#">Note 1</a> )

**Note 1:** Specification is obtained by characterization and is not 100% tested.

**2:** Design guidance only.



# HV2818/HV2918

## TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
<b>Temperature Range</b>						
Operating Temperature Range	$T_A$	0	—	+70	°C	—
Storage Temperature Range	$T_S$	-65	—	+150	°C	—
Maximum Junction Temperature	$T_J$	—	—	+125	°C	—
<b>Package Thermal Resistance</b>						
Thermal Resistance, 64-Lead QFN	$\theta_{JA}$	—	21	—	°C/W	—

TABLE 1-1: TRUTH TABLE

D0	D1	...	D15	D16	...	D31	Din	$\overline{LE}$	CLR	SW0	SW1	...	SW1 5	SW1 6	...	SW3 1
L	—		—	—		—	X	L	L	OFF	—		—	—		—
H	—		—	—		—	X	L	L	ON	—		—	—		—
—	L		—	—		—	X	L	L	—	OFF		—	—		—
—	H		—	—		—	X	L	L	—	ON		—	—		—
—	—		—	—		—	X	L	L	—	—		—	—		—
—	—		—	—		—	X	L	L	—	—		—	—		—
—	—		L	—		—	X	L	L	—	—		OFF	—		—
—	—	...	H	—	...	—	X	L	L	—	—		ON	—	...	—
—	—		—	L		—	X	L	L	—	—		—	OFF		—
—	—		—	H		—	X	L	L	—	—		—	ON		—
—	—		—	—		—	X	L	L	—	—		—	—		—
—	—		—	—		—	X	L	L	—	—		—	—		—
—	—		—	—		—	X	L	L	—	—		—	—		—
—	—		—	—		L	X	L	L	—	—		—	—		OFF
—	—		—	—		H	X	L	L	—	—		—	—		ON
X	X	X	X	X	X	X	X	H	L	HOLD PREVIOUS STATE						
X	X	X	X	X	X	X	X	X	H	ALL SWITCHES OFF						

- Note 1:** The 32 switches operate independently.  
**2:** Serial data are clocked in on the L to H transition of the CLK.  
**3:** All 32 switches go to a state retaining their latched condition at the rising edge of  $\overline{LE}$ . When  $\overline{LE}$  is low the shift registers data flow through the latch.  
**4:** D<sub>OUT</sub> is high when data in register 31 are high.  
**5:** Shift register clocking has no effect on the switch states if  $\overline{LE}$  is high.  
**6:** The CLR (clear) input overrides all the inputs.

## 1.1 Typical Timing Diagram

Figure 1-1 shows the timing of the AC characteristic parameters graphically.

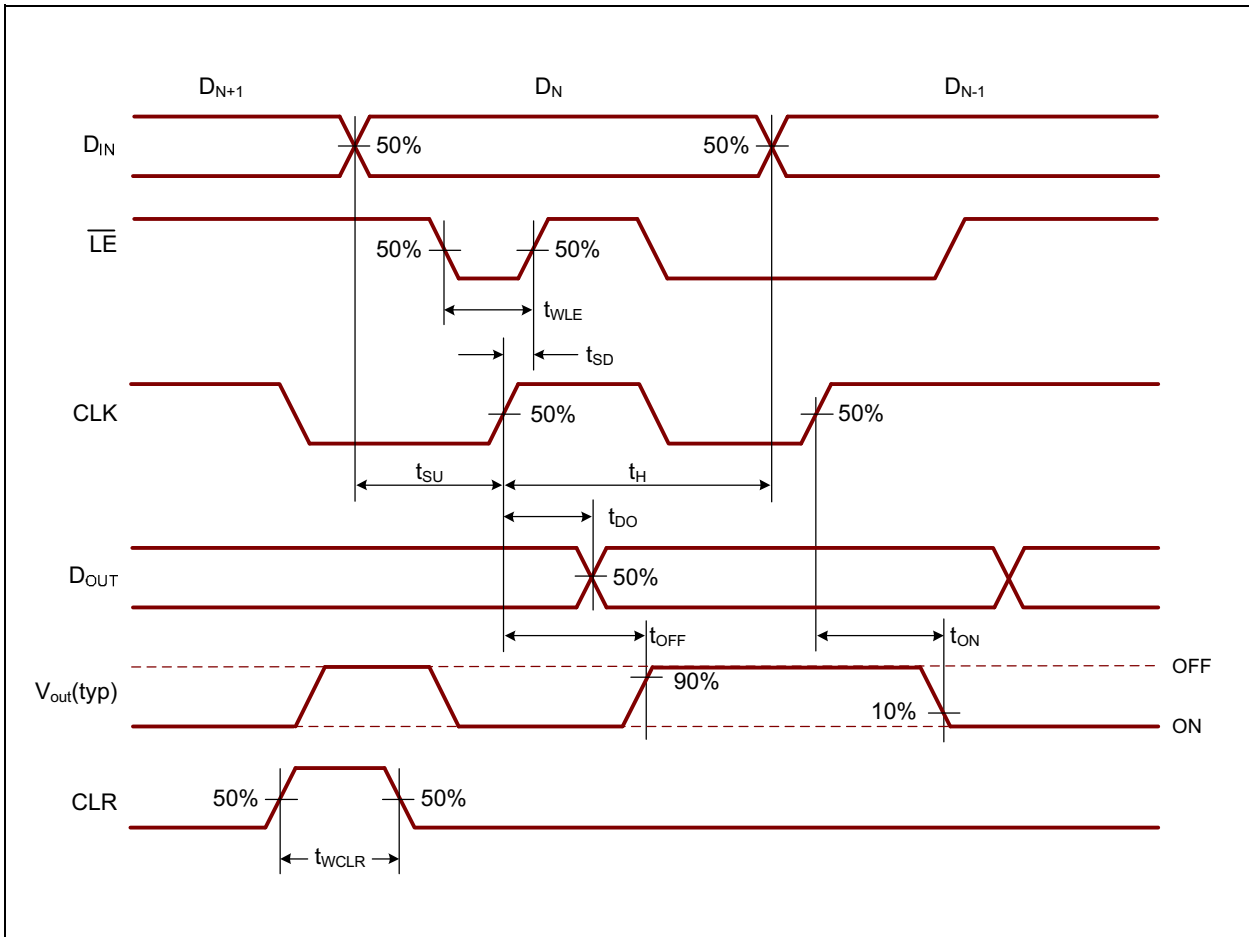


FIGURE 1-1: Logic Input Timing Diagram.

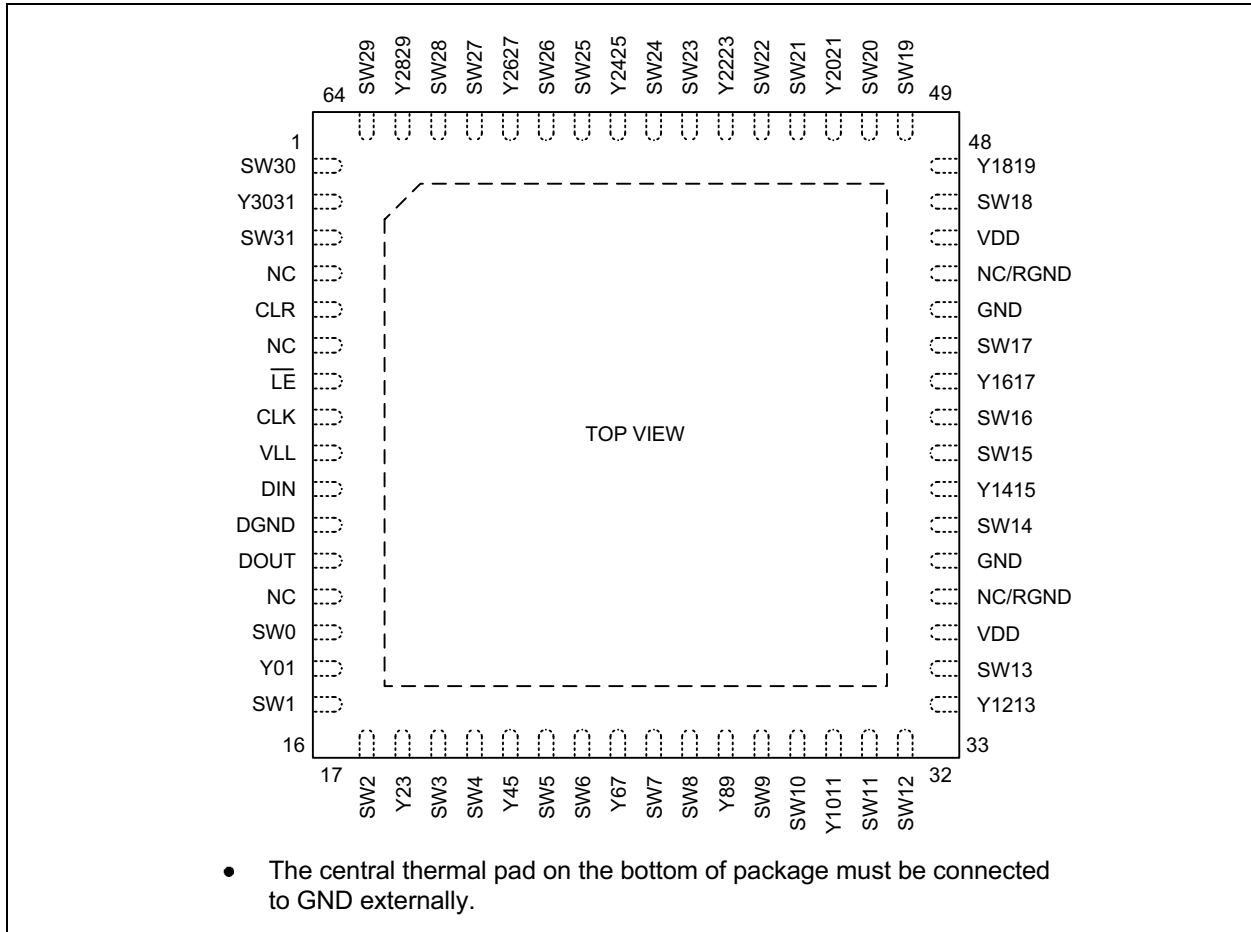
# HV2818/HV2918

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NOTES:

## 2.0 PIN DESCRIPTIONS

This section details the pin descriptions for the 64-Lead QFN package (Figure 2-1). The descriptions of the pins are listed in Table 2-1.



**FIGURE 2-1:** 64-Lead QFN Package – Top View.

**TABLE 2-1: PIN FUNCTION TABLE**

Pin Number	Symbol		Description
	HV2818	HV2918	
1	SW30	SW30	Analog Switch 30 SW Terminal; Connect to a Piezoelectric Element
2	Y3031	Y3031	Common Y Terminal of Analog Switch 30 and 31
3	SW31	SW31	Analog Switch 31 SW Terminal; Connect to a Piezoelectric Element
4	NC	NC	No Connection; Keep Floating
5	CLR	CLR	Latch Clear Logic Input
6	NC	NC	No Connection
7	$\overline{\text{LE}}$	$\overline{\text{LE}}$	Latch Enable Logic Input; Low Active
8	CLK	CLK	Clock Logic Input for Shift Register
9	V <sub>LL</sub>	V <sub>LL</sub>	Logic Supply Voltage
10	D <sub>IN</sub>	D <sub>IN</sub>	Data in Logic Input
11	DGND	DGND	Digital Ground for Logic Circuitry

# HV2818/HV2918

**TABLE 2-1: PIN FUNCTION TABLE (CONTINUED)**

Pin Number	Symbol		Description
	HV2818	HV2918	
12	D <sub>OUT</sub>	D <sub>OUT</sub>	Data Out Logic Output
13	NC	NC	No Connection; Keep Floating
14	SW0	SW0	Analog Switch 0 SW Terminal; Connect to a Piezoelectric Element
15	Y01	Y01	Common Y Terminal of Analog Switch 0 and 1
16	SW1	SW1	Analog Switch 1 SW Terminal; Connect to a Piezoelectric Element
17	SW2	SW2	Analog Switch 2 SW Terminal; Connect to a Piezoelectric Element
18	Y23	Y23	Common Y Terminal of Analog Switch 2 and 3
19	SW3	SW3	Analog Switch 3 SW Terminal; Connect to a Piezoelectric Element
20	SW4	SW4	Analog Switch 4 SW Terminal; Connect to a Piezoelectric Element
21	Y45	Y45	Common Y Terminal of Analog Switch 4 and 5
22	SW5	SW5	Analog Switch 5 SW Terminal; Connect to a Piezoelectric Element
23	SW6	SW6	Analog Switch 6 SW Terminal; Connect to a Piezoelectric Element
24	Y67	Y67	Common Y Terminal of Analog Switch 6 and 7
25	SW7	SW7	Analog Switch 7 SW Terminal; Connect to a Piezoelectric Element
26	SW8	SW8	Analog Switch 8 SW Terminal; Connect to a Piezoelectric Element
27	Y89	Y89	Common Y Terminal of Analog Switch 8 and 9
28	SW9	SW9	Analog Switch 9 SW Terminal; Connect to a Piezoelectric Element
29	SW10	SW10	Analog Switch 10 SW Terminal; Connect to a Piezoelectric Element
30	Y1011	Y1011	Common Y Terminal of Analog Switch 10 and 11
31	SW11	SW11	Analog Switch 11 SW Terminal; Connect to a Piezoelectric Element
32	SW12	SW12	Analog Switch 12 SW Terminal; Connect to a Piezoelectric Element
33	Y1213	Y1213	Common Y Terminal of Analog Switch 12 and 13
34	SW13	SW13	Analog Switch 13 SW Terminal; Connect to a Piezoelectric Element
35	V <sub>DD</sub>	V <sub>DD</sub>	Positive Supply Voltage
36	NC	RGND	No Connection/Ground for Bleed Resistor
37	GND	GND	Ground
38	SW14	SW14	Analog Switch 14 SW Terminal; Connect to a Piezoelectric Element
39	Y1415	Y1415	Common Y Terminal of Analog Switch 14 and 15
40	SW15	SW15	Analog Switch 15 SW Terminal; Connect to a Piezoelectric Element
41	SW16	SW16	Analog Switch 16 SW Terminal; Connect to a Piezoelectric Element
42	Y1617	Y1617	Common Y Terminal of Analog Switch 16 and 17
43	SW17	SW17	Analog Switch 17 SW Terminal; Connect to a Piezoelectric Element
44	GND	GND	Ground
45	NC	RGND	No Connection/Ground for Bleed Resistor
46	V <sub>DD</sub>	V <sub>DD</sub>	Positive Supply Voltage
47	SW18	SW18	Analog Switch 18 SW Terminal; Connect to a Piezoelectric Element
48	Y1819	Y1819	Common Y Terminal of Analog Switch 18 and 19
49	SW19	SW19	Analog Switch 19 SW Terminal; Connect to a Piezoelectric Element
50	SW20	SW20	Analog Switch 20 SW Terminal; Connect to a Piezoelectric Element
51	Y2021	Y2021	Common Y Terminal of Analog Switch 20 and 21
52	SW21	SW21	Analog Switch 21 SW Terminal; Connect to a Piezoelectric Element
53	SW22	SW22	Analog Switch 22 SW Terminal; Connect to a Piezoelectric Element
54	Y2223	Y2223	Common Y Terminal of Analog Switch 22 and 23

**TABLE 2-1: PIN FUNCTION TABLE (CONTINUED)**

Pin Number	Symbol		Description
	HV2818	HV2918	
55	SW23	SW23	Analog Switch 23 SW Terminal; Connect to a Piezoelectric Element
56	SW24	SW24	Analog Switch 24 SW Terminal; Connect to a Piezoelectric Element
57	Y2425	Y2425	Common Y Terminal of Analog Switch 24 and 25
58	SW25	SW25	Analog Switch 25 SW Terminal; Connect to a Piezoelectric Element
59	SW26	SW26	Analog Switch 26 SW Terminal; Connect to a Piezoelectric Element
60	Y2627	Y2627	Common Y Terminal of Analog Switch 26 and 27
61	SW27	SW27	Analog Switch 27 SW Terminal; Connect to a Piezoelectric Element
62	SW28	SW28	Analog Switch 28 SW Terminal; Connect to a Piezoelectric Element
63	Y2829	Y2829	Common Y Terminal of Analog Switch 28 and 29
64	SW29	SW29	Analog Switch 29 SW Terminal; Connect to a Piezoelectric Element
EP			The Central Thermal Pad on the Bottom of the Package Must be Connected to GND Externally

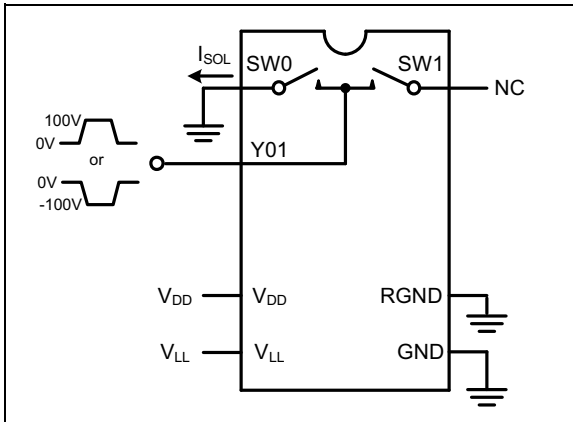
# HV2818/HV2918

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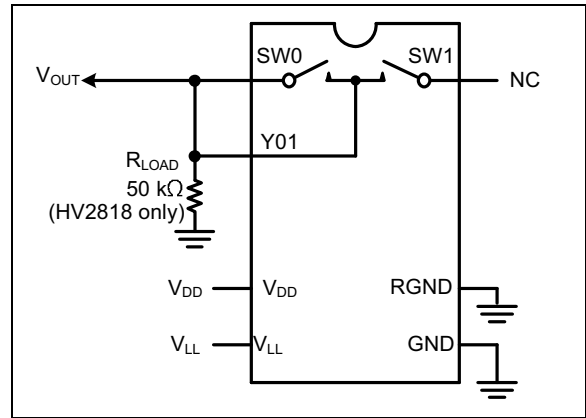
NOTES:

## 3.0 TEST CIRCUIT EXAMPLES

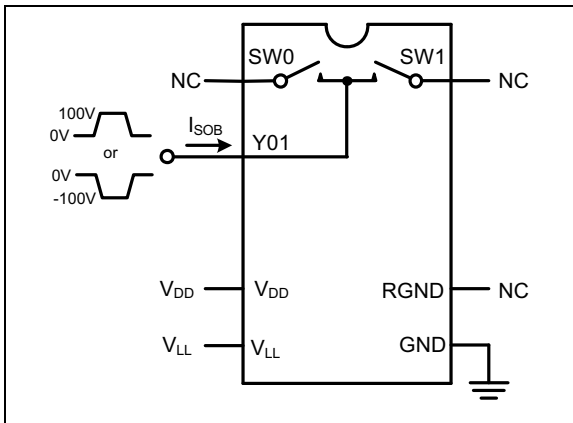
This section details a few examples of test circuits:



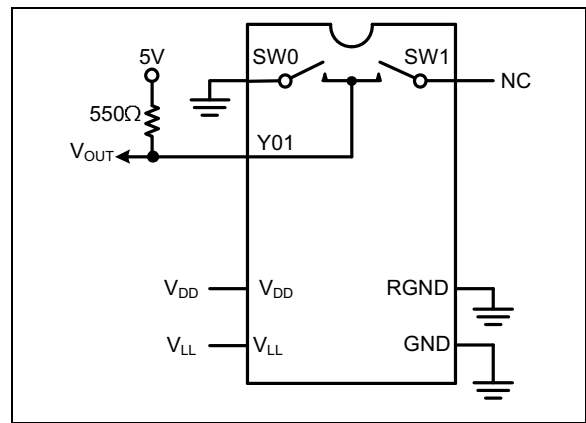
**FIGURE 3-1:** Switch-Off Leakage per Switch.



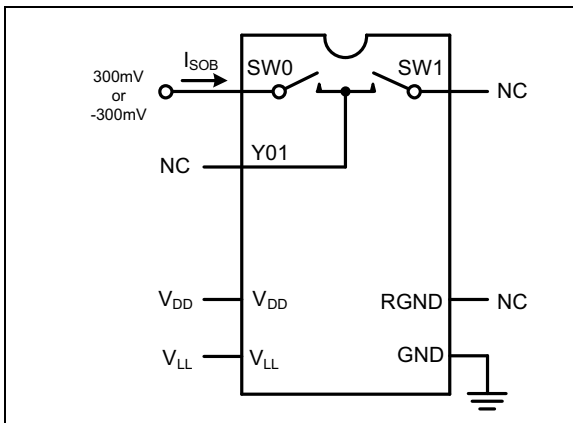
**FIGURE 3-4:** Switch DC Offset.



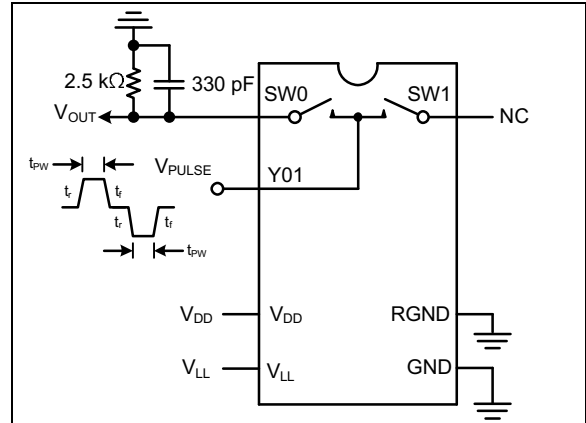
**FIGURE 3-2:** Switch-Off Bias Y.



**FIGURE 3-5:**  $T_{ON}/T_{OFF}$  Test Circuit.



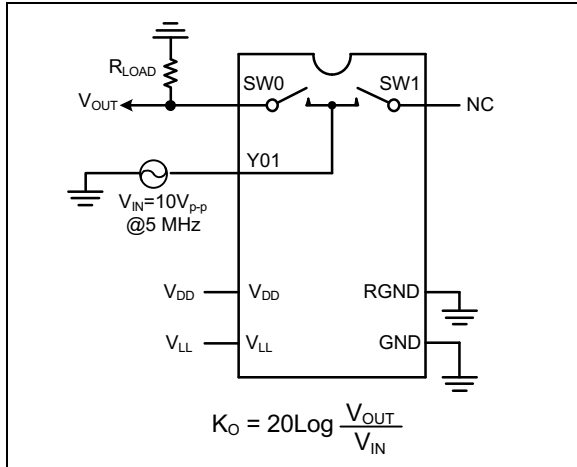
**FIGURE 3-3:** Switch-Off Bias SW.



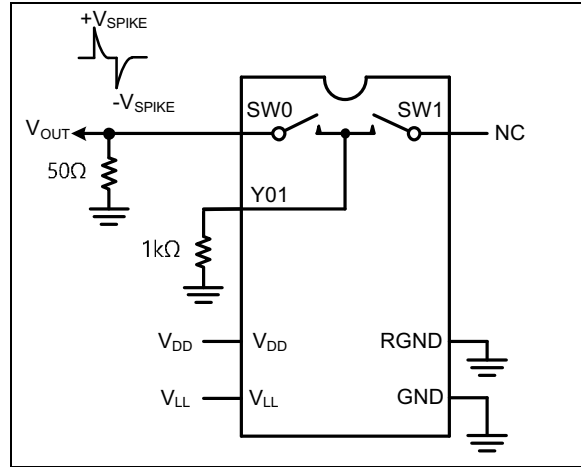
**FIGURE 3-6:** Tx Pulse Width.



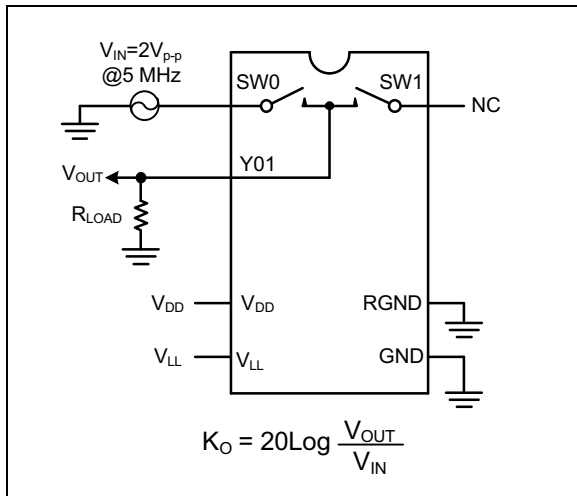
# HV2818/HV2918



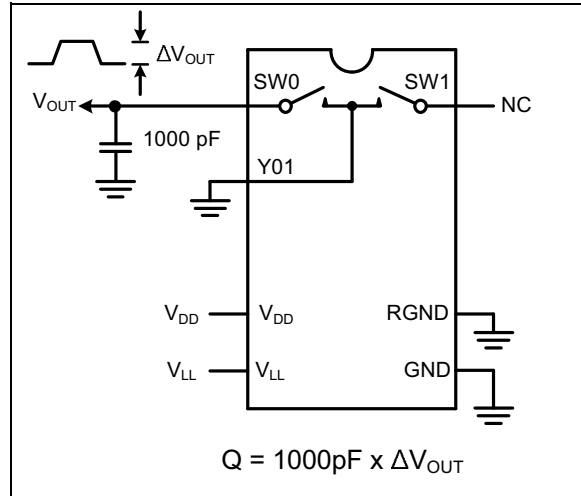
**FIGURE 3-7:** Off Isolation Y to SW.



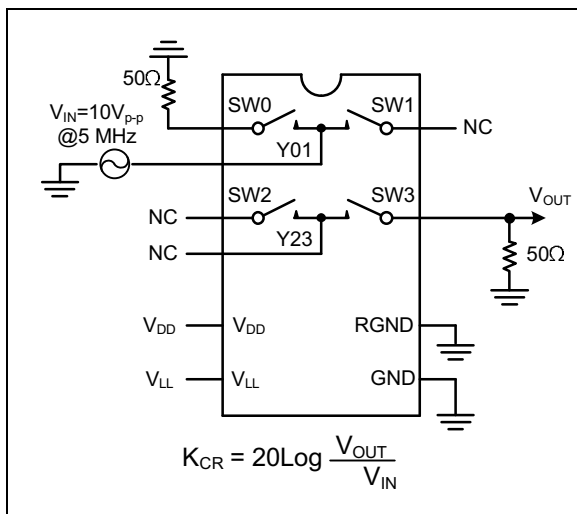
**FIGURE 3-10:** Output Voltage Spike.



**FIGURE 3-8:** Off Isolation SW to Y.



**FIGURE 3-11:** Charge Injection.

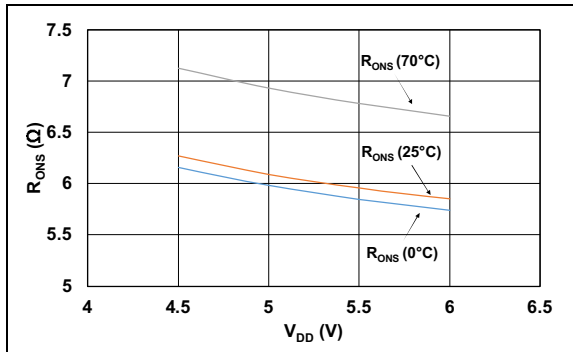


**FIGURE 3-9:** Switch Crosstalk.

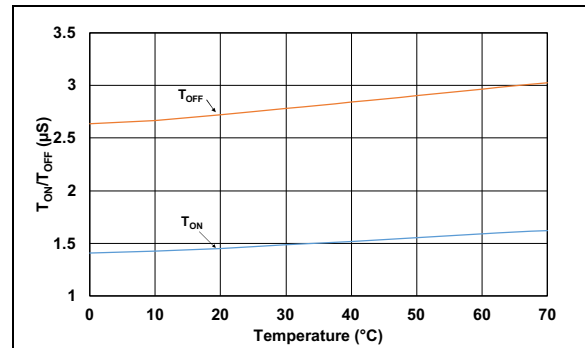
## 4.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

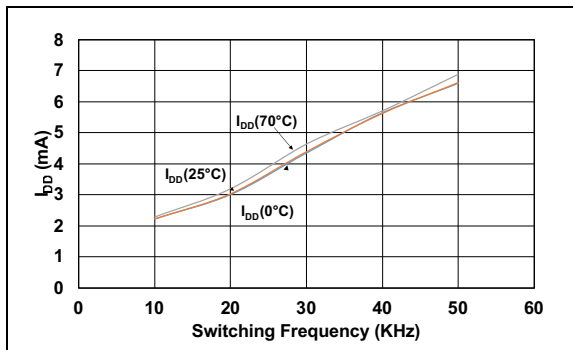
**Note:** Unless otherwise indicated:  $V_{DD} = +5V$ ,  $V_{LL} = +5V$ ,  $T_A = +25^\circ C$ .



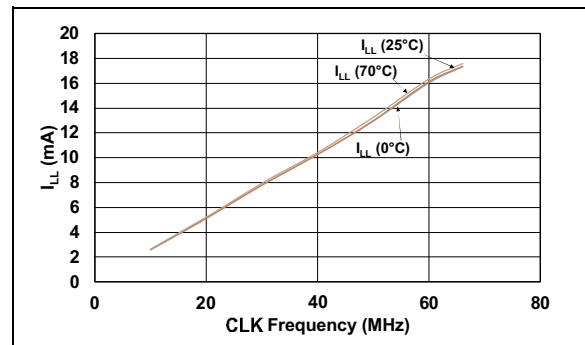
**FIGURE 4-1:**  $R_{ONS}$  at 5 mA vs.  $V_{DD}$ .



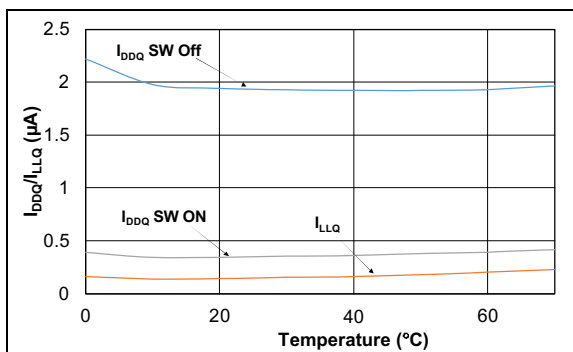
**FIGURE 4-4:**  $T_{ON}/T_{OFF}$  vs. Temperature.



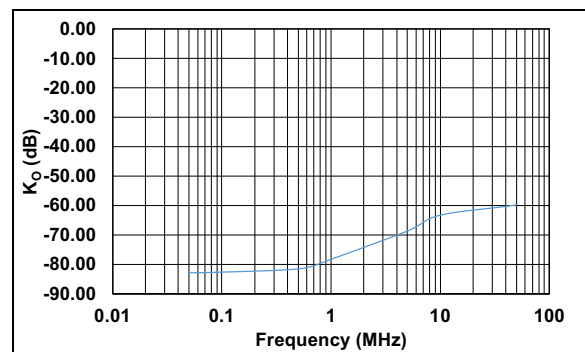
**FIGURE 4-2:**  $I_{DD}$  vs. Switching Frequency.



**FIGURE 4-5:**  $I_{LL}$  vs. CLK Frequency.



**FIGURE 4-3:**  $I_{DDQ}/I_{LLQ}$  vs. Temperature.



**FIGURE 4-6:**  $K_O$  Y to SW vs. Frequency with 50Ω Load.

# HV2818/HV2918

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NOTES:

## 5.0 DETAILED DESCRIPTION AND APPLICATION INFORMATION

### 5.1 Device Overview

The HV2818/HV2918 devices are 200V, low harmonic distortion, low charge injection, 32-channel (16 2:1 multiplexer/demultiplexer), high-voltage analog switches without high-voltage supplies. The devices require only +5V bias voltage for operation. The high-voltage analog switches are used for multiplexing a piezoelectric transducer array in a probe to multiple channel transmitter (Tx) arrays in a medical ultrasound system.

The HV2818/HV2918 are distinguished by bleed resistors that eliminate voltage build-up in capacitance loads such as piezoelectric transducers. These devices can pass  $\pm 100V$  high-voltage pulsed signal without high-voltage bias supplies such as  $\pm 100V$ . These devices have typical  $6\Omega$  ON resistance and 50 MHz bandwidth for small signals.

Like other low voltage bias switches, the HV2818/HV2918 cannot pass high-voltage DC signals. They can only pass high-voltage pulsed signals up to  $2.5\ \mu s$  pulse width.

The HV2818/HV2918 have asymmetric topology to implement smaller size compared to previous low voltage bias high-voltage switches. The SW pin can pass a high-voltage pulsed signal applied to the Y pin when the switch is ON state. When the switch is OFF state, high-voltage signal must not be applied to the SW pin due to the asymmetric topology. In medical ultrasound systems, the Y pin must be connected to AFE and the SW pin must be connected to only one piezoelectric transducer element to avoid high voltage at the SW pin during switch OFF state in the system.

Figure 5-1 shows a typical medical ultrasound image system consisting of 64 channels of transmit pulsers (Tx), 64 channels of receivers (Rx and ADC) and 64 channels of T/R switches connecting to 256 elements of an ultrasound probe via the HV2XXX high-voltage analog switch array.

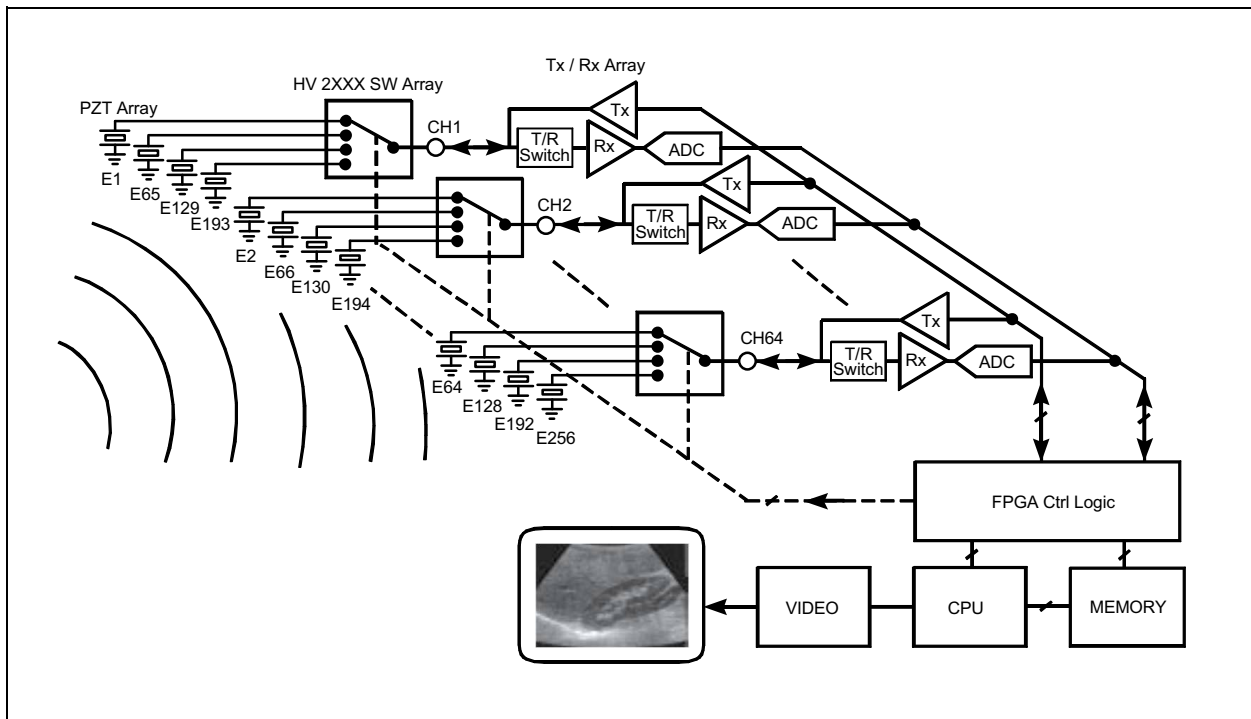


FIGURE 5-1: Typical Medical Ultrasound Imaging System.

### 5.2 Logic Input Timing

The HV2818/HV2918 have a digital serial interface consisting of Data In ( $D_{IN}$ ), Clock (CLK), Data Out ( $D_{OUT}$ ), Latch Enable (LE) and Clear (CLR) to control 32 switches independently. The digital circuits are supplied by  $V_{LL}$ . The serial clock frequency is up to 66 MHz.

The switch state configuration data, 32-bit  $D_{IN}$ , are shifted into the 32 shift registers on the rising edge (low-to-high transition) of the clock. The  $D_{OUT}$  has the same logic state of the 31<sup>st</sup> shift register data. The switch Configuration bit of SW31 is shifted in first and the Configuration bit of SW0 is shifted in last. To change all the switch ON/OFF states at the same time, the LE must remain high while the 32-bit Data In signal is shifted into the 32-bit register.

# HV2818/HV2918

After the valid 32-bit data complete shifting into the shift registers, the high-to-low transition of the  $\overline{LE}$  signal transfers the contents of the shift registers into the latches. Finally, setting the  $\overline{LE}$  back to high allows all the latches to keep the current state while new data can be shifted into the shift registers without disturbing the latches.

It is recommended to change all the latch states at the same time through this method to avoid possible clock feed through noise (see Figure 5-2 for details).

When the CLR input is set high, it resets the data of all 32 latches to low. Consequently, all the high-voltage switches are set to OFF state. However, the CLR signal does not affect the contents of the shift register, so the shift register can operate independently of the CLR signal. Therefore, the shift register still retains the previous data when the CLR input is low (see Table 1-1 for details).

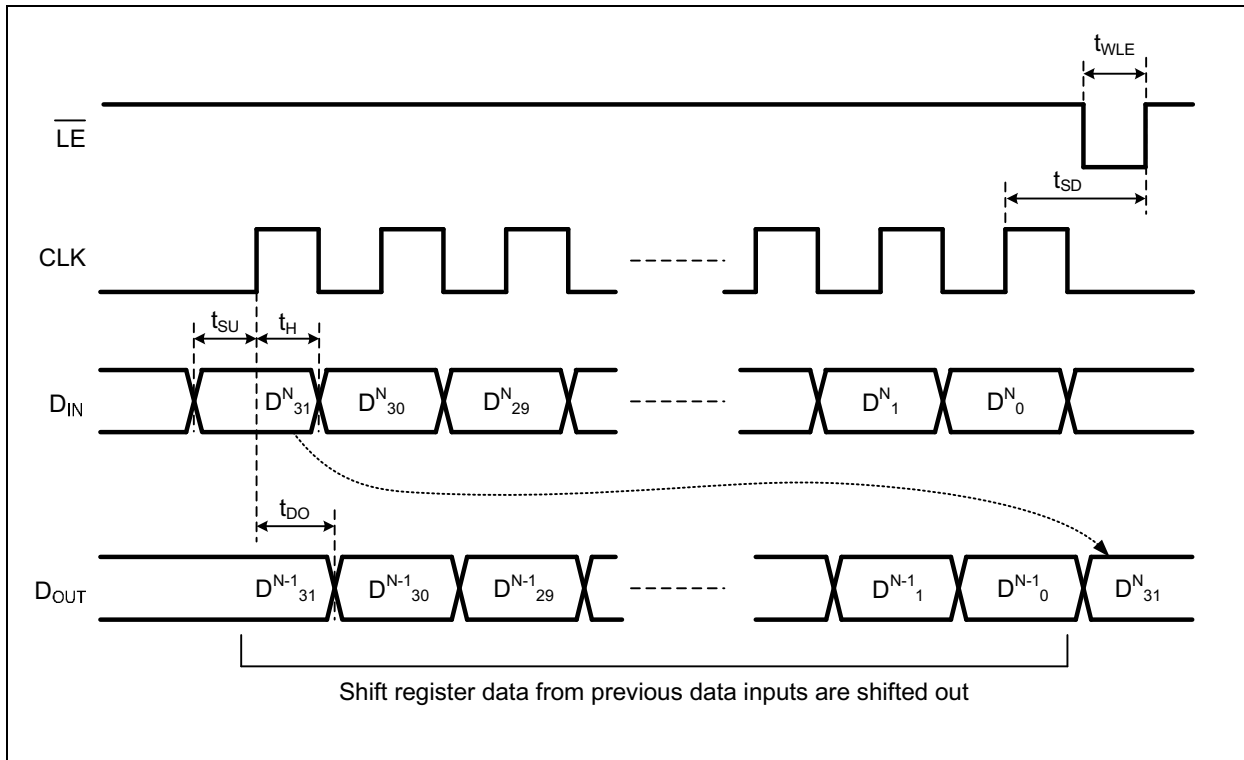


FIGURE 5-2: Latch Enable Timing Diagram.

## 5.3 Multiple Devices Connection

The digital serial interface of the HV2818/HV2918 allows multiple devices to daisy-chain architecture. In daisy-chain architecture,  $D_{OUT}$  of the first device is connected to the  $D_{IN}$  of the second device, and so forth. The last  $D_{OUT}$  of the daisy-chained HV2818/HV2918 can be either floating or fed back to an FPGA to check the previously stored shift register data. CLK, CLR and  $\overline{LE}$  of daisy-chained devices can be connected to each other to save the number of control signal from FPGA.

To control all the high-voltage analog switch states in daisy-chained N devices,  $N \times 32$  bits of data are shifted into shift registers along with  $N \times 32$  clocks, while  $\overline{LE}$  remains high and CLR remains low. After all the data finish shifting in, one single negative pulse of  $\overline{LE}$  transfers the data from shift registers to latches simultaneously. Consequently, all  $N \times 32$  high-voltage analog switches change states simultaneously.

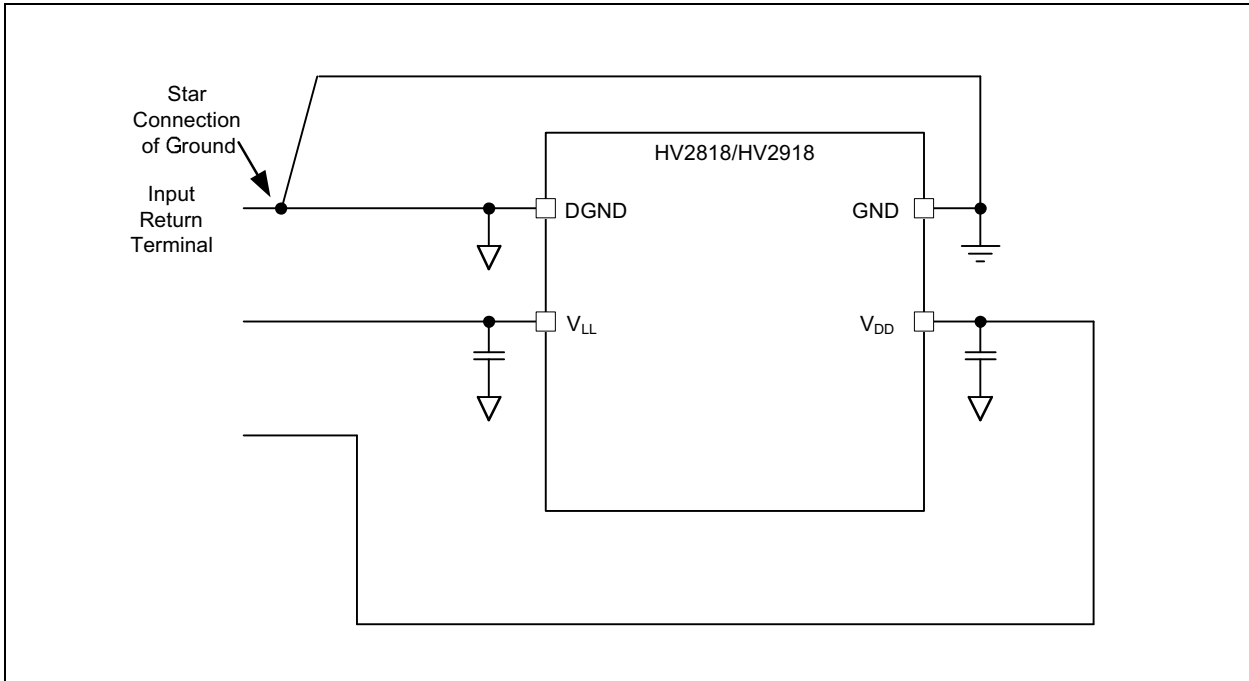
## 5.4 Power-Up/Down Sequence

The recommended power-up sequence of the HV2818/HV2918 is  $V_{LL}$  first then  $V_{DD}$ . The power-down sequence is in reverse order of power-up. During the power-up/down period, all the analog switch inputs must be within  $V_{DD}$  and GND or floating.

## 5.5 Layout Considerations

The HV2818/HV2918 devices have two separate ground connections. DGND is the ground connection for digital circuitry, and GND is the ground connection for substrate and analog switches. High-transient current passes through the switches and returns through GND in the ultrasound system. The high-current path needs to be designed as short as possible to avoid ground bouncing.

It is recommended to use two separate ground planes in the PCB, connected together at the return terminal of the input power line, as shown in Figure 5-3. It is recommended that 0.1  $\mu\text{F}$  or larger ceramic decoupling capacitors, with low Equivalent Series Resistance (ESR) and appropriate voltage rating, be connected between DGND and power supplies,  $V_{LL}$  and  $V_{DD}$ . These decoupling capacitors must be placed as close as possible to the device in the PCB layout.



**FIGURE 5-3:** Layout Guidelines.

# HV2818/HV2918

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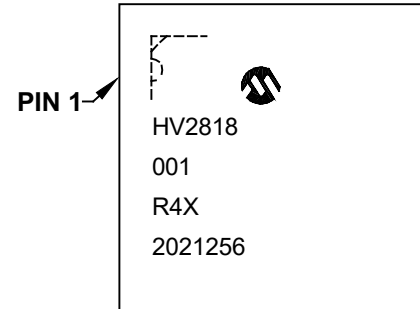
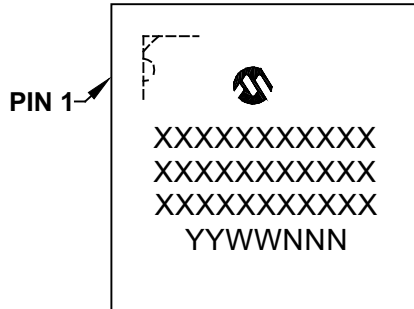
NOTES:

## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

64-Lead QFN (9 x 9 x 0.9 mm)

Example



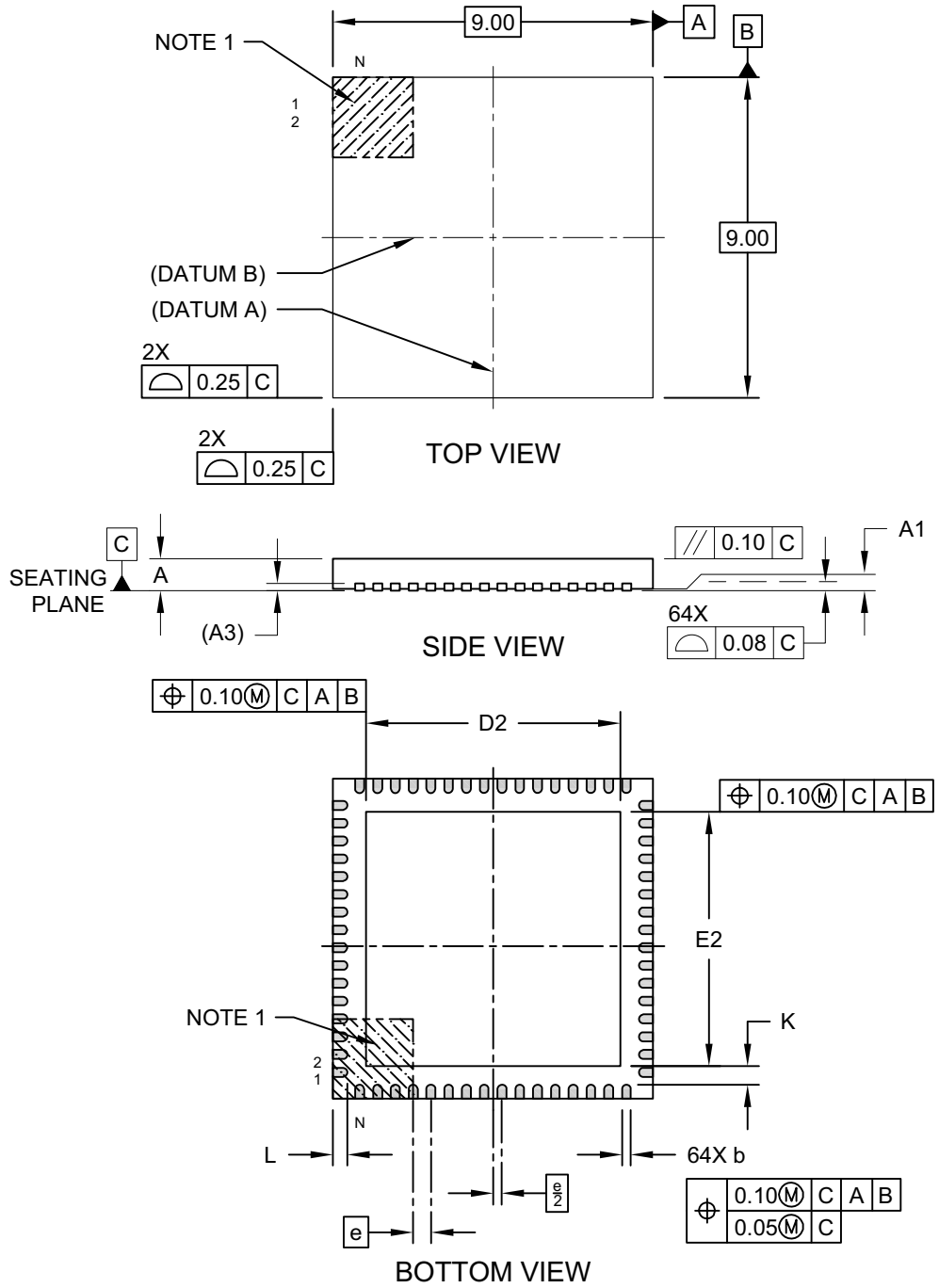
<b>Legend:</b>	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	



# HV2818/HV2918

## 64-Lead Very Thin Plastic Quad Flat, No Lead Package (R4X) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

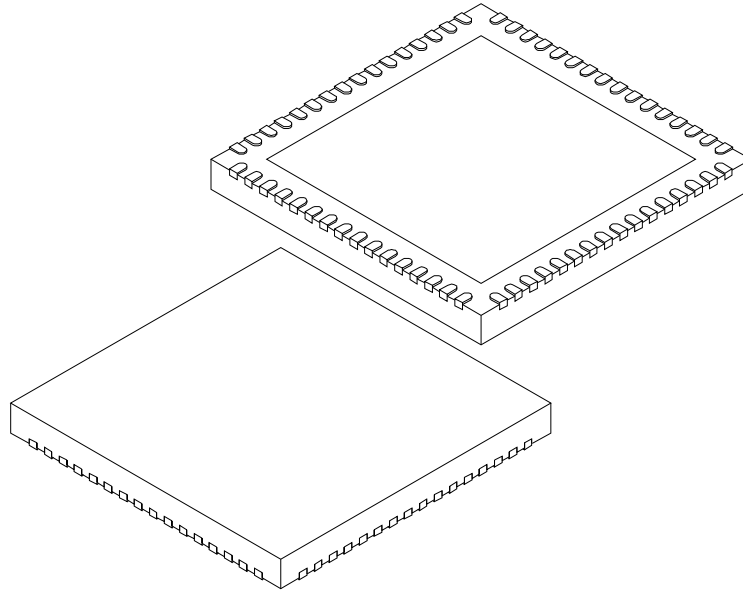
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-149D [R4X] Sheet 1 of 2

## 64-Lead Very Thin Plastic Quad Flat, No Lead Package (R4X) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	7.05	7.15	7.25
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	7.05	7.15	7.25
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

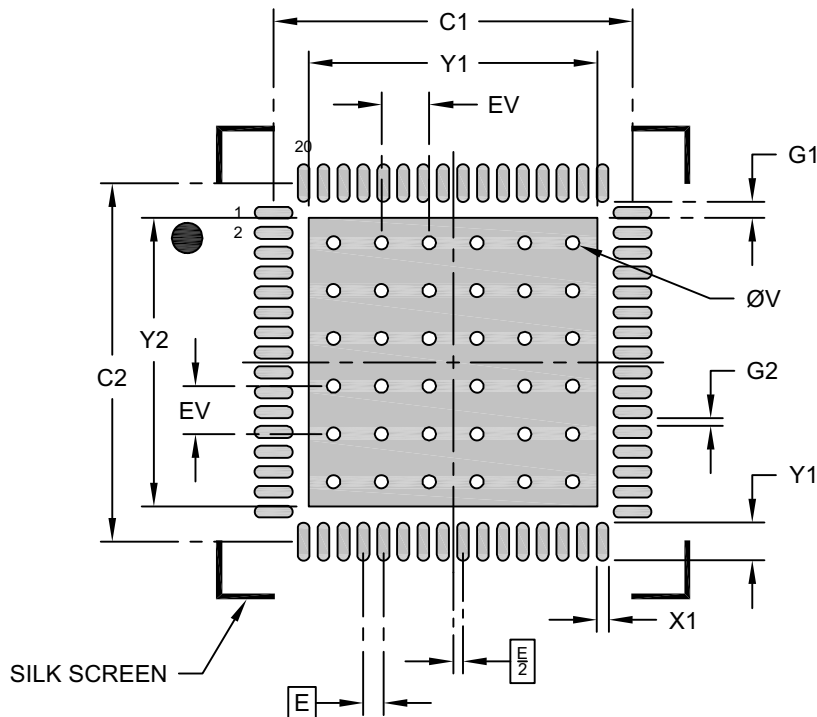
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149D [R4X] Sheet 2 of 2

# HV2818/HV2918

## 64-Lead Very Thin Plastic Quad Flat, No Lead Package (R4X) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			7.25
Optional Center Pad Length	Y2			7.25
Contact Pad Spacing	C1		9.00	
Contact Pad Spacing	C2		9.00	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.95
Contact Pad to Center Pad (X64)	G1	0.40		
Spacing Between Contact Pads (X60)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

**Notes:**

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2149C [R4X]

## APPENDIX A: REVISION HISTORY

### Revision B (August 2021)

The following is the list of modifications:

- Updated [Note 1](#) in table [Recommended Operating Conditions](#).
- Updated parameter “Off Isolation SW to Y” in table [AC Electrical Characteristics](#).
- Various typographical errors.

### Revision A (June 2020)

- Initial release of this document.

# HV2818/HV2918

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NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		
Device	<u>/XX</u>	Package Type
<b>Device:</b>	HV2818:	No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch
	HV2918:	No High-Voltage Bias, Low Harmonic Distortion, 32-Channel, High-Voltage Analog Switch with Bleed Resistor
<b>Temperature:</b>	N	= 0°C to +70°C (Commercial)
<b>Package Type:</b>	R4X	= Very Thin Plastic Quad Flat Pack, No Lead Package, 64-LD QFN

**Examples:**

a) HV2818/R4X: Commercial temperature, Very Thin Plastic Quad Flat, 64-LD QFN package

b) HV2918/R4X: Commercial temperature, Very Thin Plastic Quad Flat, 64-LD QFN package

# HV2818/HV2918

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NOTES:

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**Note the following details of the code protection feature on Microchip devices:**

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